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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	16980
Number of Logic Elements/Cells	360000
Total RAM Bits	23946240
Number of I/O	342
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-HBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agzme3e3h29c4n

Symbol	Description	Maximum	Unit
$I_{XCVR\text{-}RX\ (DC)}$	DC current per transceiver receiver (RX) pin	50	mA

Internal Weak Pull-Up Resistor

All I/O pins, except configuration, test, and JTAG pins, have an option to enable weak pull-up.

Table 1-13: Internal Weak Pull-Up Resistor Values for Arria V Devices

Symbol	Description	Condition (V)[11]	Value[12]	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you have enabled the programmable pull-up resistor option.	V_{CCIO} = 3.3 ±5%	25	kΩ
		V_{CCIO} = 3.0 ±5%	25	kΩ
		V_{CCIO} = 2.5 ±5%	25	kΩ
		V_{CCIO} = 1.8 ±5%	25	kΩ
		V_{CCIO} = 1.5 ±5%	25	kΩ
		V_{CCIO} = 1.35 ±5%	25	kΩ
		V_{CCIO} = 1.25 ±5%	25	kΩ
		V_{CCIO} = 1.2 ±5%	25	kΩ

Related Information

Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines

Provides more information about the pins that support internal weak pull-up and internal weak pull-down features.

(10) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C\ dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

(11) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

(12) Valid with ±10% tolerances to cover changes over PVT.

Protocol	Sub-protocol	Data Rate (Mbps)
SONET	SONET 155	155.52
	SONET 622	622.08
	SONET 2488	2,488.32
Gigabit-capable passive optical network (GPON)	GPON 155	155.52
	GPON 622	622.08
	GPON 1244	1,244.16
	GPON 2488	2,488.32
QSGMII	QSGMII 5000	5,000

Core Performance Specifications

Clock Tree Specifications

Table 1-35: Clock Tree Specifications for Arria V Devices

Parameter	Performance			Unit
	–I3, –C4	–I5, –C5	–C6	
Global clock and Regional clock	625	625	525	MHz
Peripheral clock	450	400	350	MHz

PLL Specifications

Table 1-36: PLL Specifications for Arria V Devices

This table lists the Arria V PLL block specifications. Arria V PLL block does not include HPS PLL.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
t_{OUTPJ_DC}[67]	Period jitter for dedicated clock output in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	175	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	17.5	mUI (p-p)
t_{FOUTPJ_DC}[67]	Period jitter for dedicated clock output in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	250[68], 175[69]	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	25[68], 17.5[69]	mUI (p-p)
t_{OUTCCJ_DC}[67]	Cycle-to-cycle jitter for dedicated clock output in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	175	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	17.5	mUI (p-p)
$t_{FOUTCCJ\_DC}$[67]	Cycle-to-cycle jitter for dedicated clock output in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	250[68], 175[69]	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	25[68], 17.5[69]	mUI (p-p)
t_{OUTPJ_IO}[67][70]	Period jitter for clock output on a regular I/O in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
t_{FOUTPJ_IO}[67][68][70]	Period jitter for clock output on a regular I/O in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
t_{OUTCCJ_IO}[67][70]	Cycle-to-cycle jitter for clock output on a regular I/O in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
$t_{FOUTCCJ\_IO}$[67][68][70]	Cycle-to-cycle jitter for clock output on a regular I/O in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)

(67) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Memory Output Clock Jitter Specification for Arria V Devices table.

(68) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05–0.95 must be ≥ 1000 MHz.

(69) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be ≥ 1200 MHz.

(70) External memory interface clock output jitter specifications use a different measurement method, which are available in Memory Output Clock Jitter Specification for Arria V Devices table.

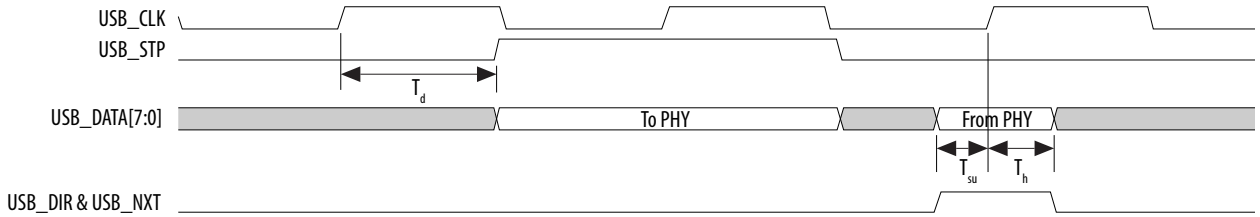
Symbol	Condition	–I3, –C4			–I5, –C5			–C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	SERDES factor J ≥ 8[76][78], LVDS TX with RX DPA	[77]	—	1600	[77]	—	1500	[77]	—	1250	Mbps
	SERDES factor J = 1 to 2, Uses DDR Registers	[77]	—	[79]	[77]	—	[79]	[77]	—	[79]	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Network - f_{HSDR} (data rate)[80]	SERDES factor J = 4 to 10[81]	[77]	—	945	[77]	—	945	[77]	—	945	Mbps
Emulated Differential I/O Standards with One External Output Resistor Network - f_{HSDR} (data rate)[80]	SERDES factor J = 4 to 10[81]	[77]	—	200	[77]	—	200	[77]	—	200	Mbps
$t_{x\ Jitter}$ -True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	UI

(78) The V_{CC} and V_{CCP} must be on a separate power layer and a maximum load of 5 pF for chip-to-chip interface.
(79) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}), provided you can close the design timing and the signal integrity simulation is clean.
(80) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.
(81) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Symbol	Description	Min	Max	Unit
T_h	SPI MISO hold time	1	—	ns
$T_{dutycycle}$	SPI_CLK duty cycle	45	55	%
$T_{dssfrst}$	Output delay SPI_SS valid before first clock edge	8	—	ns
T_{dsslst}	Output delay SPI_SS valid after last clock edge	8	—	ns
T_{dio}	Master-out slave-in (MOSI) output delay	–1	1	ns

(86) This value is based on `rx_sample_dly` = 1 and `spi_m_clk` = 120 MHz. `spi_m_clk` is the internal clock that is used by SPI Master to derive it's `SCLK_OUT`. These timings are based on `rx_sample_dly` of 1. This delay can be adjusted as needed to accommodate slower response times from the slave. Note that a delay of 0 is not allowed. The setup time can be used as a reference starting point. It is very crucial to do a calibration to get the correct `rx_sample_dly` value because each SPI slave device may have different output delay and each application board may have different path delay. For more information about `rx_sample_delay`, refer to the SPI Controller chapter in the Hard Processor System Technical Reference Manual.

Figure 1-12: USB Timing Diagram

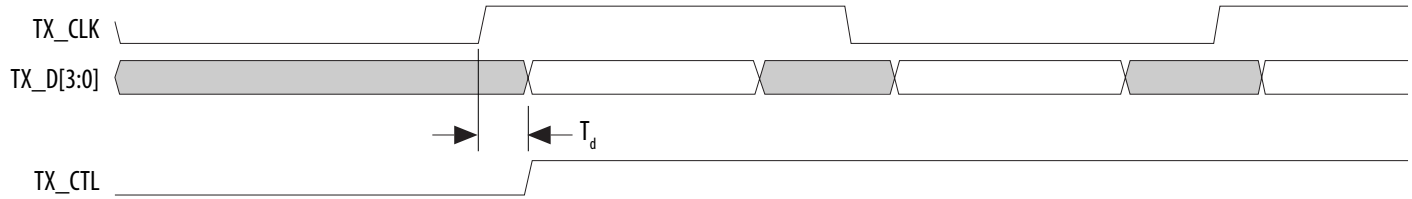


Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 1-56: Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
$T_{dutycycle}$	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	–0.85	—	0.15	ns

Figure 1-13: RGMII TX Timing Diagram



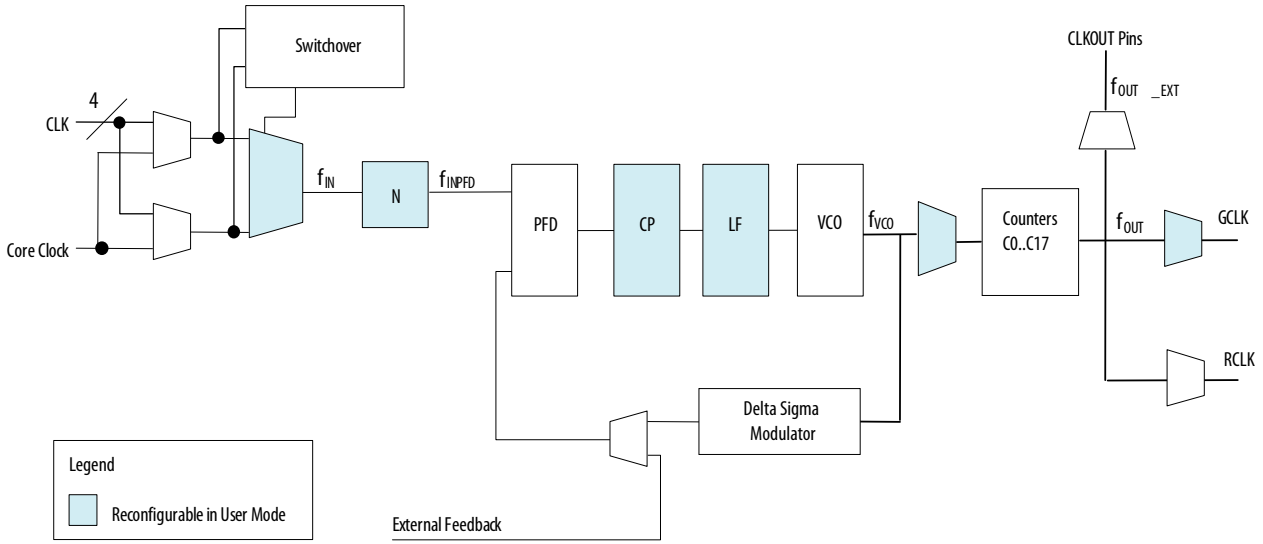
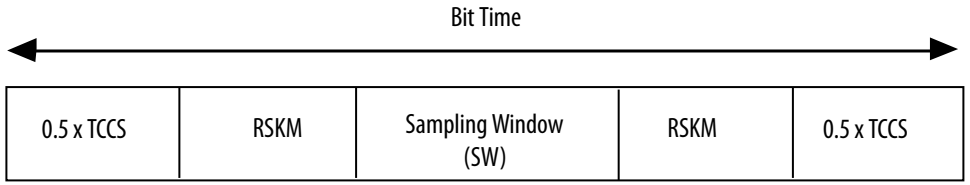
Variant	Member Code	Active Serial[108]			Fast Passive Parallel[109]		
		Width	DCLK (MHz)	Minimum Configuration Time (ms)	Width	DCLK (MHz)	Minimum Configuration Time (ms)
Arria V GX	A1	4	100	178	16	125	36
	A3	4	100	178	16	125	36
	A5	4	100	255	16	125	51
	A7	4	100	255	16	125	51
	B1	4	100	344	16	125	69
	B3	4	100	344	16	125	69
	B5	4	100	465	16	125	93
	B7	4	100	465	16	125	93
Arria V GT	C3	4	100	178	16	125	36
	C7	4	100	255	16	125	51
	D3	4	100	344	16	125	69
	D7	4	100	465	16	125	93
Arria V SX	B3	4	100	465	16	125	93
	B5	4	100	465	16	125	93
Arria V ST	D3	4	100	465	16	125	93
	D5	4	100	465	16	125	93

Related Information

Configuration Files on page 1-83

(108) DCLK frequency of 100 MHz using external CLKUSR.

(109) Maximum FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Term	Definition
PLL specifications	Diagram of PLL specifications  **Note:** (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.
R_L	Receiver differential input discrete resistor (external to the Arria V device).
Sampling window (SW)	Timing diagram—The period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position in the sampling window, as shown: 

Date	Version	Changes
July 2014	3.8	• Added a note in Table 3, Table 4, and Table 5: The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements. • Updated V_{CC_HPS} specification in Table 5. • Added a note in Table 19: Differential inputs are powered by V_{CCPD} which requires 2.5 V. • Updated "Minimum differential eye opening at the receiver serial input pins" specification in Table 20 and Table 21. • Updated description in "HPS PLL Specifications" section. • Updated VCO range maximum specification in Table 39. • Updated T_d and T_h specifications in Table 45. • Added T_h specification in Table 47 and Figure 13. • Updated a note in Figure 20, Figure 21, and Figure 23 as follows: Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required. • Removed "Remote update only in AS mode" specification in Table 58. • Added DCLK device initialization clock source specification in Table 60. • Added description in "Configuration Files" section: The IOCSR `.rbf` size is specifically for the Configuration via Protocol (CvP) feature. • Removed $f_{MAX\_RU\_CLK}$ specification in Table 63.
February 2014	3.7	• Updated $V_{CCRSTCLK\_HPS}$ maximum specification in Table 1. • Added $V_{CC\_AUX\_SHARED}$ specification in Table 1.
December 2013	3.6	• Added "HPS PLL Specifications". • Added Table 24, Table 39, and Table 40. • Updated Table 1, Table 3, Table 5, Table 19, Table 20, Table 21, Table 38, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, Table 48, Table 49, Table 50, Table 51, Table 55, Table 56, and Table 59. • Updated Figure 7, Figure 13, Figure 15, Figure 16, and Figure 19. • Removed table: GPIO Pulse Width for Arria V Devices.

Date	Version	Changes
June 2012	2.0	• Updated for the Quartus II software v12.0 release: • Restructured document. • Updated "Supply Current and Power Consumption" section. • Updated Table 20, Table 21, Table 24, Table 25, Table 26, Table 35, Table 39, Table 43, and Table 52. • Added Table 22, Table 23, and Table 33. • Added Figure 1–1 and Figure 1–2. • Added "Initialization" and "Configuration Files" sections.
February 2012	1.3	• Updated Table 2–1. • Updated Transceiver-FPGA Fabric Interface rows in Table 2–20. • Updated V_{CCP} description.
December 2011	1.2	Updated Table 2–1 and Table 2–3.
November 2011	1.1	• Updated Table 2–1, Table 2–19, Table 2–26, and Table 2–36. • Added Table 2–5. • Added Figure 2–4.
August 2011	1.0	Initial release.

Arria V GZ Device Datasheet

2

2017.02.10

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This document covers the electrical and switching characteristics for Arria V GZ devices. Electrical characteristics include operating conditions and power consumption. Switching characteristics include transceiver specifications, core, and periphery performance. This document also describes I/O timing, including programmable I/O element (IOE) delay and programmable output buffer delay.

Related Information

Arria V Device Overview
For information regarding the densities and packages of devices in the Arria V GZ family.

Electrical Characteristics

Operating Conditions

When you use Arria V GZ devices, they are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of Arria V GZ devices, you must consider the operating requirements described in this datasheet.

Arria V GZ devices are offered in commercial and industrial temperature grades.

Commercial devices are offered in –3 (fastest) and –4 core speed grades. Industrial devices are offered in –3L and –4 core speed grades. Arria V GZ devices are offered in –2 and –3 transceiver speed grades.

Table 2-1: Commercial and Industrial Speed Grade Offering for Arria V GZ Devices

C = Commercial temperature grade; I = Industrial temperature grade.

Lower number refers to faster speed grade.

L = Low power devices.

Transceiver Speed Grade	Core Speed Grade			
	C3	C4	I3L	I4
2	Yes	—	Yes	—
3	—	Yes	—	Yes

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Arria V GZ devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.

Caution: Conditions other than those listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 2-2: Absolute Maximum Ratings for Arria V GZ Devices

Symbol	Description	Minimum	Maximum	Unit
V_{CC}	Power supply for core voltage and periphery circuitry	–0.5	1.35	V
V_{CCPT}	Power supply for programmable power technology	–0.5	1.8	V
V_{CCPGM}	Power supply for configuration pins	–0.5	3.9	V
V_{CC_AUX}	Auxiliary supply for the programmable power technology	–0.5	3.4	V
V_{CCBAT}	Battery back-up power supply for design security volatile key register	–0.5	3.9	V
V_{CCPD}	I/O pre-driver power supply	–0.5	3.9	V
V_{CCIO}	I/O power supply	–0.5	3.9	V
V_{CCD_FPLL}	PLL digital power supply	–0.5	1.8	V
V_{CCA_FPLL}	PLL analog power supply	–0.5	3.4	V

Related Information

- **PowerPlay Early Power Estimator User Guide**
  For more information about the EPE tool.
- **PowerPlay Power Analysis**
  For more information about PowerPlay power analysis.

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus II PowerPlay Power Analyzer feature.

Note: You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- **PowerPlay Early Power Estimator User Guide**
  For more information about the EPE tool.
- **PowerPlay Power Analysis**
  For more information about PowerPlay power analysis.

I/O Pin Leakage Current

Table 2-8: I/O Pin Leakage Current for Arria V GZ Devices

If $V_O = V_{CCIO}$ to $V_{CCIOMax}$, 100 µA of leakage current per I/O is expected.

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0$ V to $V_{CCIOMAX}$	–30	—	30	µA
I_{OZ}	Tri-stated I/O pin	$V_O = 0$ V to $V_{CCIOMAX}$	–30	—	30	µA

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	0.49 × V_{CCIO}	0.5 × VCCIO	0.51 × V_{CCIO}
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	0.49 × V_{CCIO}	0.5 × VCCIO	0.51 × V_{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V_{CCIO}/2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V_{CCIO}/2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 × V_{CCIO}	0.5 × V_{CCIO}	0.53 × V_{CCIO}	—	V_{CCIO}/2	—
HSUL-12	1.14	1.2	1.3	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	—	—	—

Table 2-18: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V GZ Devices

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{ol} (mA)	I_{oh} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.608	V_{TT} + 0.608	8.1	–8.1
SSTL-2 Class II	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.81	V_{TT} + 0.81	16.2	–16.2
SSTL-18 Class I	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCIO} + 0.3	V_{REF} – 0.25	V_{REF} + 0.25	V_{TT} – 0.603	V_{TT} + 0.603	6.7	–6.7

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
`fixedclk` clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	MHz
Reconfiguration clock (`mgmt_clk_clk`) frequency	—	100	—	125	100	—	125	MHz

Related Information

Arria V Device Overview

For more information about device ordering codes.

Receiver

Table 2-24: Receiver Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O Standards	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS							
Data rate (Standard PCS) (143), (144)	—	600	—	9900	600	—	8800	Mbps
Data rate (10G PCS) (143), (144)	—	600	—	12500	600	—	10312.5	Mbps
Absolute V_{MAX} for a receiver pin (145)	—	—	—	1.2	—	—	1.2	V
Absolute V_{MIN} for a receiver pin	—	–0.4	—	—	–0.4	—	—	V

(143) The line data rate may be limited by PCS-FPGA interface speed grade.
(144) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.
(145) The device cannot tolerate prolonged operation at this absolute maximum.

Description	Min	Typ	Max	Unit
Diode ideality factor	1.006	1.008	1.010	—

Periphery Performance

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

Note: The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

High-Speed Clock Specifications

Table 2-39: High-Speed Clock Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

For LVDS applications, you must use the PLLs in integer PLL mode.

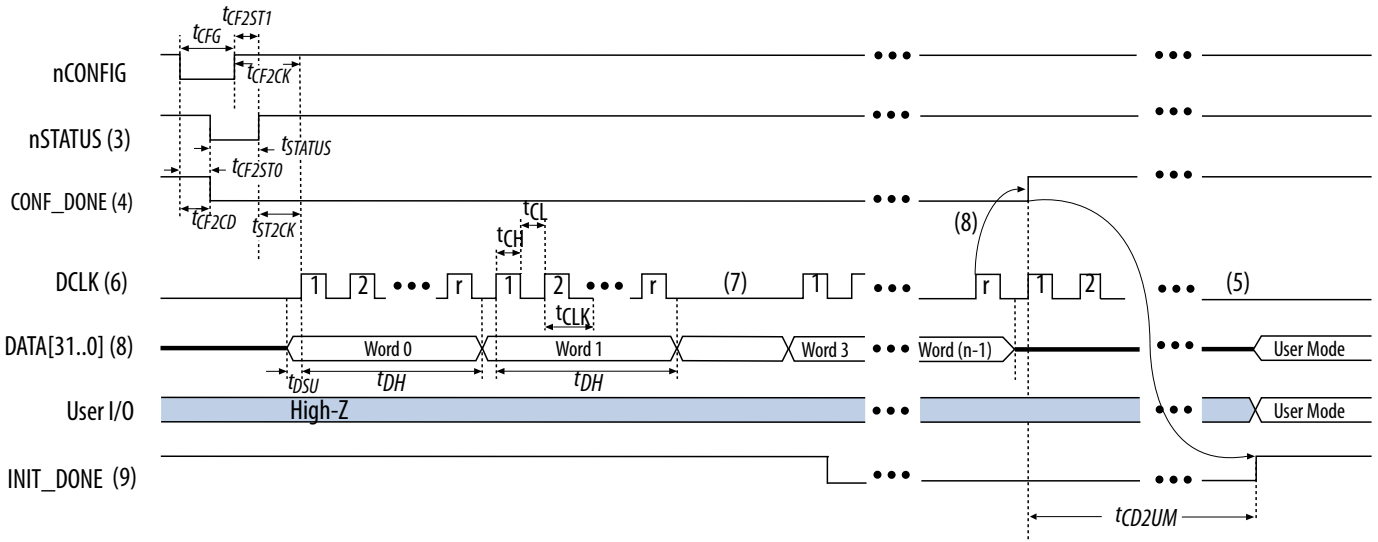
Arria V GZ devices support the following output standards using true LVDS output buffer types on all I/O banks.

- True RSDS output standard with data rates of up to 230 Mbps
- True mini-LVDS output standard with data rates of up to 340 Mbps

FPP Configuration Timing when DCLK to DATA[] > 1

Figure 2-8: FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 ,

Timing when using a MAX II device, MAX V device, or microprocessor as an external host.



Notes:

1. To find out the DCLK-to-DATA[] ratio for your system, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.
2. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
3. After power-up, the Arria V GZ device holds nSTATUS low for the time as specified by the POR delay.
4. After power-up, before and during configuration, CONF_DONE is low.
5. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
6. "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.
7. If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA[31..0] pins prior to sending the first DCLK rising edge.
8. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF_DONE is released high after the Arria V GZ device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
9. After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CO}	DCLK falling edge to AS_DATA0/ASDO output	—	4	ns
t_{SU}	Data setup time before falling edge on DCLK	1.5	—	ns
t_{H}	Data hold time after falling edge on DCLK	0	—	ns
t_{CD2UM}	CONF_DONE high to user mode (216)	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period)	—	—

Table 2-59: DCLK Frequency Specification in the AS Configuration Scheme

This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Related Information

- **Passive Serial Configuration Timing** on page 2-67
- **Configuration, Design Security, and Remote System Upgrades in Arria V Devices**

(216) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the "Initialization" section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

Related Information

Configuration, Design Security, and Remote System Upgrades in Arria V Devices

Initialization

Table 2-61: Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices

Initialization Clock Source	Configuration Schemes	Maximum Frequency (MHz)	Minimum Number of Clock Cycles
Internal Oscillator	AS, PS, FPP	12.5	8576
CLKUSR (222)	PS, FPP	125	
	AS	100	
DCLK	PS, FPP	125	

Configuration Files

Use the following table to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal file (`.hex`) or tabular text file (`.ttf`) format, have different file sizes.

For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size.

(221) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

(222) To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** panel of the **Device and Pin Options** dialog box.

Date	Version	Changes

June 2016	2016.06.20	• Changed column heading from "Value" to "Maximum" in the "Pin Capacitance for Arria V GZ Devices" table.
		• Changed the minimum supported data rate range values from "1000" to "2000" in the "ATX PLL Specifications for Arria V GZ Devices" table.
		• Added the supported data rates for the following output standards using true LVDS output buffer types in the "High-Speed Clock Specifications for Arria V GZ Devices" table:
		  • True RSDS output standard: data rates of up to 230 Mbps
		  • True mini-LVDS output standard: data rates of up to 340 Mbps

December 2015	2015.12.16	• Removed the CDR ppm tolerance specification from the "Receiver Specifications for Arria V GZ Devices" table. • Removed transmitter rise and fall time specifications from the "Transmitter Specifications for Arria V GZ Devices" table. • Changed the .rbf sizes in the "Uncompressed .rbf Sizes for Arria V GZ Devices" table. • Added a footnote to the "Transmitter High-Speed I/O Specifications for Arria V GZ Devices" table.
June 2015	2015.06.16	• Changed the conditions for the reference clock rise and fall time and added a note to the condition in the "Reference Clock Specifications for Arria V GZ Devices" table. • Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Receiver Specifications for Arria V GZ Devices" table.
January 2015	2015.01.30	• Added 240-Ω to the "OCT Calibration Accuracy Specifications for Arria V GZ Devices" table. • Changed the CDR PPM tolerance spec in the "Receiver Specifications for Arria V GZ Devices" table. • Added additional max data rate for fPLL in the "Fractional PLL Specifications for Arria V GZ Devices" table.